

### Features

- Single 5 V  $\pm 5\%$  power supply
- N channel, silicon gate, depletion load technology
- Eight bit parallel processing
- 56 Instructions
- Decimal and binary arithmetic
- Thirteen addressing modes
- True indexing capability
- Programmable stack pointer
- Variable length stack
- Interrupt capability
- Non-maskable interrupt
- Use with any type or speed memory
- Bi-directional Data Bus
- Instruction decoding and control
- Addressable memory range of up to 65 K bytes
- "Ready" input
- Direct memory access capability
- Bus compatible with MC6800
- Choice of external or on-board clocks
- 1 MHz, 2 MHz, 3 MHz and 4 MHz operation
- On-chip clock options
  - \* External single clock input
  - \* Crystal time base input
- 40 and 28 pin package versions
- Pipeline architecture

### Description

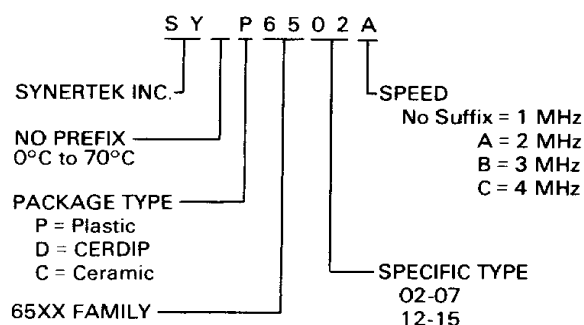
The SY6500 Series Microprocessors represent the first totally software compatible microprocessor family. This family of products includes a range of software compatible microprocessors which provide a selection of addressable memory range, interrupt input options and on-chip clock oscillators and drivers. All of the microprocessors in the SY6500 family are software compatible within the group and are bus compatible with the MC6800 product offering.

The family includes six microprocessors with on-board clock oscillators and drivers and four microprocessors driven by external clocks. The on-chip clock versions are aimed at high performance, low cost applications where single phase inputs or crystals provide the time base. The external clock versions are geared for the multi-processor system applications where maximum timing control is mandatory. All versions of the microprocessors are available in 1 MHz, 2 MHz, 3 MHz and 4 MHz maximum operating frequencies.

### Members of the Family

PART NUMBERS	CLOCKS	PINS	$\overline{IRQ}$	$\overline{NMI}$	RYD	ADDRESSING
SY6502	On-Chip	40	✓	✓	✓	64 K
SY6503	"	28	✓	✓		4 K
SY6504	"	28	✓			8 K
SY6505	"	28	✓		✓	4 K
SY6506	"	28	✓			4 K
SY6507	"	28			✓	8 K
SY6512	External	40	✓	✓	✓	64 K
SY6513	"	28	✓	✓		4 K
SY6514	"	28	✓			8 K
SY6515	"	28	✓		✓	4 K

### Ordering Information

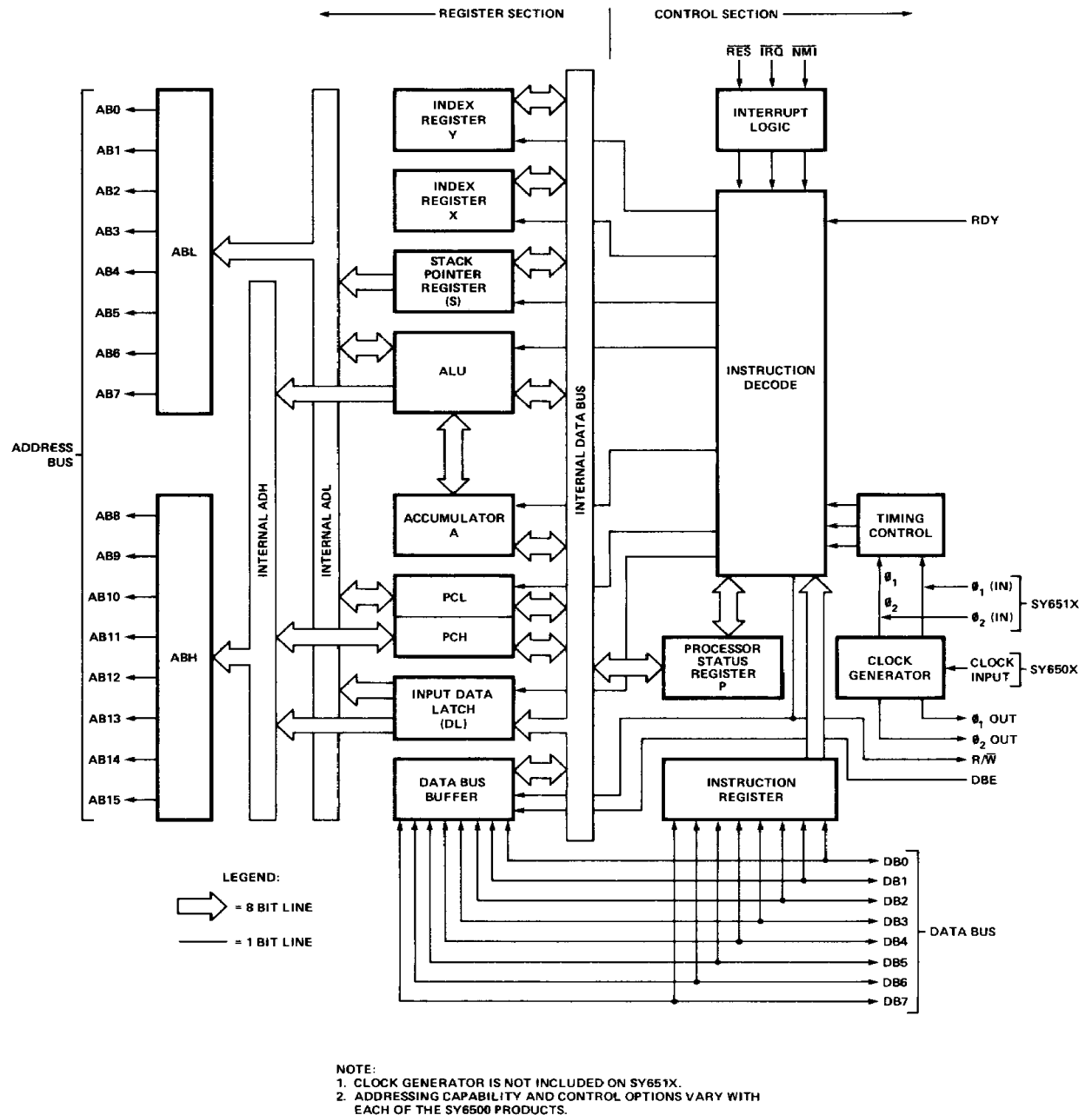


Only 6502 and 6512 are available in 3 and 4 MHz

### Comments on the Data Sheet

The data sheet is constructed to review first the basic "Common Characteristics" — those features which are common to the general family of microprocessors. Subsequent to a review of the family characteristics will be sections devoted to each member of the group with specific features of each.

### SY6500 Internal Architecture



## Absolute Maximum Ratings\*

Rating	Symbol	Value	Unit
Supply Voltage	$V_{CC}$	-0.3 to +7.0	V
Input Voltage	$V_{in}$	-0.3 to +7.0	V
Operating Temperature	$T_A$	0 to +70	°C
Storage Temperature	$T_{STG}$	-55 to +150	°C

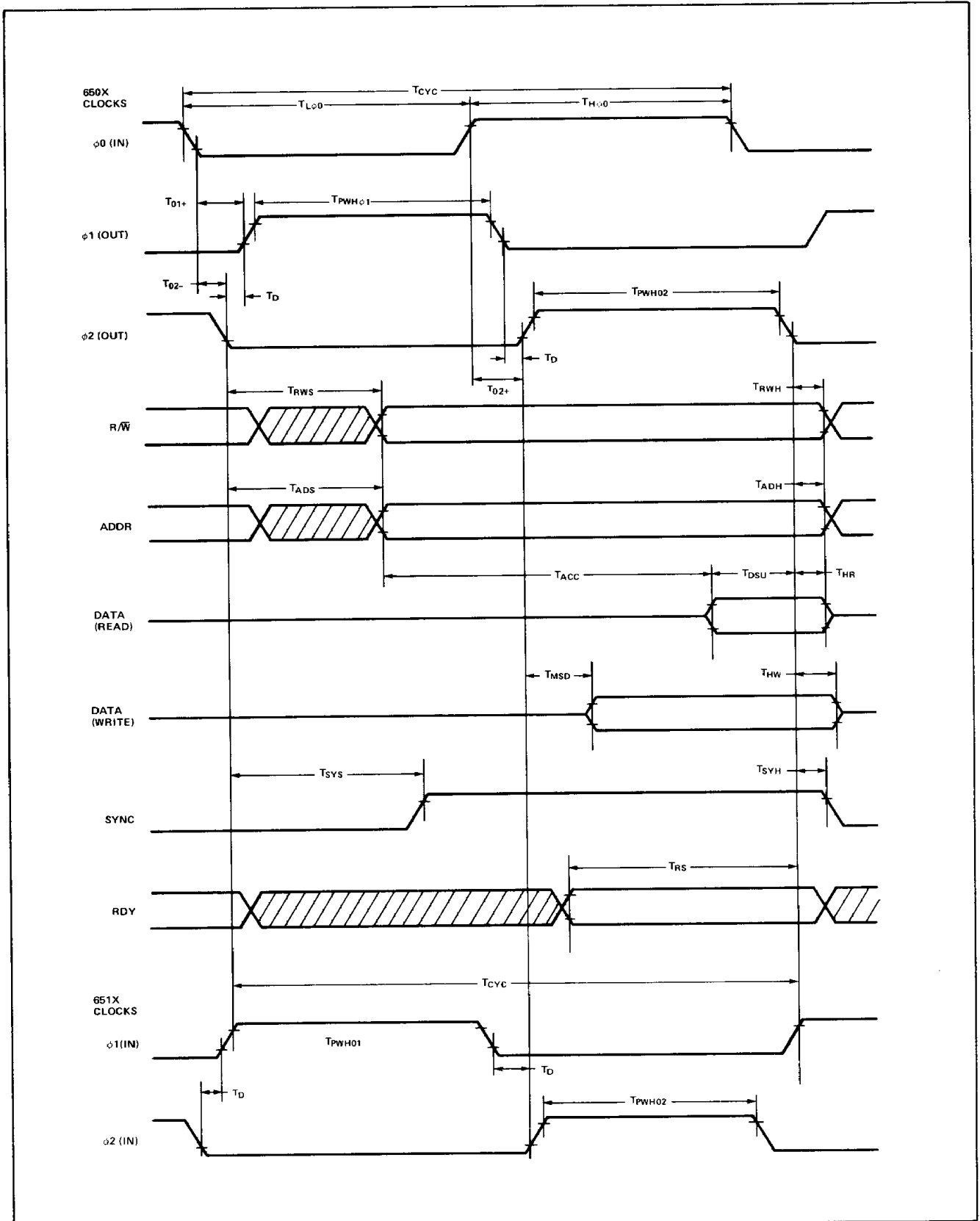
## Comment\*

This device contains input protection against damage due to high static voltages or electric fields; however, precautions should be taken to avoid application of voltages higher than the maximum rating.

D.C. Characteristics ( $V_{CC} = 5.0V \pm 5\%$ ,  $T_A = 0-70^\circ C$ )

( $\emptyset_1, \emptyset_2$  applies to SY651X,  $\emptyset_{o(in)}$  applies to SY650X)

Symbol	Characteristic	Min.	Max.	Unit
$V_{IH}$	Input High Voltage Logic and $\emptyset_o$ (in) for all 650X devices	1,2,3 MHz 4 MHz	$V_{CC}$ $V_{CC}$	V V
	$\emptyset_1$ and $\emptyset_2$ only for all 651X devices. Logic as 650X	All Speeds	$V_{CC} - 0.5$ $V_{CC} + 0.25$	V
$V_{IL}$	Input Low Voltage Logic, $\emptyset_{o(in)}$ (650X) $\emptyset_1, \emptyset_2$ (651X)	-0.3 -0.3	+0.8 +0.2	V
$I_{IL}$	Input Loading ( $V_{in} = 0V$ , $V_{CC} = 5.25V$ ) RDY, S.O.	-10	-300	$\mu A$
$I_{in}$	Input Leakage Current ( $V_{in} = 0$ to $5.25V$ , $V_{CC} = 0$ ) Logic (Excl. RDY, S.O.)	—	2.5	$\mu A$
	$\emptyset_1, \emptyset_2$ (651X)	—	100	$\mu A$
	$\emptyset_{o(in)}$ (650X)	—	10.0	$\mu A$
$I_{TSI}$	Three-State (Off State) Input Current ( $V_{in} = 0.4$ to $2.4V$ , $V_{CC} = 5.25V$ ) DB0-DB7	—	$\pm 10$	$\mu A$
$V_{OH}$	Output High Voltage ( $I_{LOAD} = -100\mu A$ , $V_{CC} = 4.75V$ ) 1,2,3 MHz SYNC, DB0-DB7, A0-A15, R/ $\bar{W}$ 4 MHz	2.4 2.0	— —	V V
$V_{OL}$	Output Low Voltage ( $I_{LOAD} = 1.6mA$ , $V_{CC} = 4.75V$ ) 1,2,3 MHz SYNC, DB0-DB7, A0-A15, R/ $\bar{W}$ 4 MHz	— —	0.4 0.8	V V
$P_D$	Power Dissipation ( $V_{CC} = 5.25V$ ) 1 MHz and 2 MHz 3 MHz 4 MHz	— — —	700 800 900	mW mW mW
C	Capacitance ( $V_{in} = 0$ , $T_A = 25^\circ C$ , $f = 1MHz$ )			
$C_{in}$	RES, NMi, RDY, $\bar{IRQ}$ , S.O., DBE DB0-DB7	— —	10 15	pF
$C_{out}$	A0-A15, R/ $\bar{W}$ , SYNC	—	12	
$C_{\emptyset_{o(in)}}$	$\emptyset_{o(in)}$ (650X)	—	15	
$C_{\emptyset_1}$	$\emptyset_1$ (651X)	—	50	
$C_{\emptyset_2}$	$\emptyset_2$ (651X)	—	80	



## Dynamic Operating Characteristics

(V<sub>CC</sub> = 5.0 ± 5%, T<sub>A</sub> = 0° to 70°C)

Parameter	Symbol	1 MHz		2 MHz		3 MHz		4 MHz		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>651X</b>										
Cycle Time	T <sub>CYC</sub>	1.00	40	0.50	40	0.33	40	0.25	40	μs
φ <sub>1</sub> Pulse Width	T <sub>PWH01</sub>	430	—	215	—	150	—			ns
φ <sub>2</sub> Pulse Width	T <sub>PWH02</sub>	470	—	235	—	160	—			ns
Delay Between φ <sub>1</sub> and φ <sub>2</sub>	T <sub>D</sub>	0	—	0	—	0	—			ns
φ <sub>1</sub> and φ <sub>2</sub> Rise and Fall Times <sup>(1)</sup>	T <sub>R</sub> , T <sub>F</sub>	0	25	0	20	0	15			ns
<b>650X</b>										
Cycle Time	T <sub>CYC</sub>	1.00	40	0.50	40	0.33	40	0.25	40	μs
φ <sub>0(IN)</sub> Low Time <sup>(2)</sup>	T <sub>L00</sub>	480	—	240	—	160	—	110	—	ns
φ <sub>0(IN)</sub> High Time <sup>(2)</sup>	T <sub>H00</sub>	460	—	240	—	160	—	115	—	ns
φ <sub>0</sub> Neg to φ <sub>1</sub> Pos Delay <sup>(5)</sup>	T <sub>D01+</sub>	10	70	10	70	10	70	10	70	ns
φ <sub>0</sub> Neg to φ <sub>2</sub> Neg Delay <sup>(5)</sup>	T <sub>D02-</sub>	5	65	5	65	5	65	5	65	ns
φ <sub>0</sub> Pos to φ <sub>1</sub> Neg Delay <sup>(5)</sup>	T <sub>D01-</sub>	5	65	5	65	5	65	5	65	ns
φ <sub>0</sub> Pos to φ <sub>2</sub> Pos Delay <sup>(5)</sup>	T <sub>D02+</sub>	15	75	15	75	15	75	15	75	ns
φ <sub>0(IN)</sub> Rise and Fall Time <sup>(1)</sup>	T <sub>RO</sub> , T <sub>FO</sub>	0	30	0	20	0	15	0	10	ns
φ <sub>1(OUT)</sub> Pulse Width	T <sub>PWH01</sub>	T <sub>L00</sub> -20	T <sub>L00</sub>	T <sub>L00</sub> -20	T <sub>L00</sub>	T <sub>L00</sub> -20	T <sub>L00</sub>	T <sub>L00</sub> -20	T <sub>L00</sub>	ns
φ <sub>2(OUT)</sub> Pulse Width	T <sub>PWH02</sub>	T <sub>L00</sub> -40	T <sub>L00</sub> -10	T <sub>L00</sub> -40	T <sub>L00</sub> -10	T <sub>L00</sub> -40	T <sub>L00</sub> -10	T <sub>L00</sub> -40	T <sub>L00</sub> -10	ns
Delay Between φ <sub>1</sub> and φ <sub>2</sub>	T <sub>D</sub>	5	—	5	—	5	—	5	—	ns
φ <sub>1</sub> and φ <sub>2</sub> Rise and Fall Times <sup>(1,3)</sup>	T <sub>R</sub> , T <sub>F</sub>	—	25	—	25	—	15	—	15	ns
<b>650X, 651X</b>										
R/W Setup Time	T <sub>RWS</sub>	—	225	—	140	—	110	—	90	ns
R/W Hold Time	T <sub>RWH</sub>	30	—	30	—	15	—	10	—	ns
Address Setup Time	T <sub>ADS</sub>	—	225	—	140	—	110	—	90	ns
Address Hold Time	T <sub>ADH</sub>	30	—	30	—	15	—	10	—	ns
Read Access Time	T <sub>ACC</sub>	—	650	—	310	—	170	—	110	ns
Read Data Setup Time	T <sub>DSU</sub>	100	—	50	—	50	—	50	—	ns
Read Data Hold Time	T <sub>HR</sub>	10	—	10	—	10	—	10	—	ns
Write Data Setup Time	T <sub>MDS</sub>	20	175	20	100	20	75	—	70	ns
Write Data Hold Time	T <sub>HW</sub>	60	150	60	150	30	130	20	—	ns
Sync Setup Time	T <sub>SYS</sub>	—	350	—	175	—	100	—	90	ns
Sync Hold Time	T <sub>SYH</sub>	30	—	30	—	15	—	15	—	ns
RDY Setup Time <sup>(4)</sup>	T <sub>RS</sub>	200	—	200	—	150	—	120	—	ns

## NOTES:

1. Measured between 10% and 90% points.
2. Measured at 50% points.
3. Load = 1 TTL load +30 pF.
4. RDY must never switch states within T<sub>RS</sub> to end of φ<sub>2</sub>.
5. Load = 100 pF.
6. The 2 MHz devices are identified by an "A" suffix.
7. The 3 MHz devices are identified by a "B" suffix.
8. The 4 MHz devices are identified by a "C" suffix.

## TIMING DIAGRAM NOTE:

Because the clock generation for the SY650X and SY651X is different, the two clock timing sections are referenced to the main timing diagram by three reference lines marked REF 'A', REF 'B' and REF 'C'. Reference between the two sets of clock timings is without meaning. Timing parameters are referred to these lines and scale variations in the diagrams are of no consequence.

## Pin Functions

### Clocks ( $\phi_1, \phi_2$ )

The SY651X requires a two phase non-overlapping clock that runs at the  $V_{CC}$  voltage level.

The SY650X clocks are supplied with an internal clock generator. The frequency of these clocks is externally controlled. Clock generator circuits are shown elsewhere in this data sheet.

**Address Bus ( $A_0-A_{15}$ )** (See sections on each micro for respective address lines on those devices.)

These outputs are TTL compatible, capable of driving one standard TTL load and 130 pF.

### Data Bus ( $DB_0-DB_7$ )

Eight pins are used for the data bus. This is a bi-directional bus, transferring data to and from the device and peripherals. The outputs are three-state buffers, capable of driving one standard TTL load and 130 pF.

### Data Bus Enable (DBE)

This TTL compatible input allows external control of the three-state data output buffers and will enable the microprocessor bus driver when in the high state. In normal operation DBE would be driven by the phase two ( $\phi_2$ ) clock, thus allowing data output from microprocessor only during  $\phi_2$ . During the read cycle, the data bus drivers are internally disabled, becoming essentially an open circuit. To disable data bus drivers externally, DBE should be held low. This signal is available on the SY6512, only.

### Ready (RDY)

This input signal allows the user to halt the microprocessor on all cycles except write cycles. A negative transition to the low state during or coincident with phase one ( $\phi_1$ ) will halt the microprocessor with the output address lines reflecting the current address being fetched. This condition will remain through a subsequent phase two ( $\phi_2$ ) in which the Ready signal is low. This feature allows microprocessor interfacing with low speed PROMS as well as fast (max. 2 cycle) Direct Memory Access (DMA). If ready is low during a write cycle, it is ignored until the following read operation. Ready transitions must not be permitted during  $\phi_2$  time.

### Interrupt Request ( $\overline{IRQ}$ )

This TTL level input requests that an interrupt sequence begin within the microprocessor. The microprocessor will complete the current instruction being executed before recognizing the request. At that time, the interrupt mask bit in the Status Code Register will be examined. If the interrupt mask flag is not set, the microprocessor will begin an interrupt sequence. The Program Counter and Processor Status Register are stored in the stack. The microprocessor will then set the interrupt mask flag high so that no further interrupts may occur. At the end of this cycle, the program counter low will be loaded from address FFFE, and program counter high from location FFFF, therefore transferring program control to the memory vector located at these addresses. The RDY signal must be in the high state for any interrupt to be recognized. A 3K $\Omega$  external resistor should be used for proper wire-OR operation.

### Non-Maskable Interrupt ( $\overline{NMI}$ )

A negative going transition on this input requests that a non-maskable interrupt sequence be generated within the microprocessor.

$\overline{NMI}$  is an unconditional interrupt. Following completion of the current instruction, the sequence of operations defined for  $\overline{IRQ}$  will be performed, regardless of the state interrupt mask flag. The vector address loaded into the program counter, low and high, are locations FFFA and FFFB respectively, thereby transferring program control to the memory vector located at these addresses. The instructions loaded at these locations cause the microprocessor to branch to a non-maskable interrupt routine in memory.

$\overline{NMI}$  also requires an external 3K $\Omega$  resistor to  $V_{CC}$  for proper wire-OR operations.

Inputs  $\overline{IRQ}$  and  $\overline{NMI}$  are hardware interrupts lines that are sampled during  $\phi_2$  (phase 2) and will begin the appropriate interrupt routine on the  $\phi_1$  (phase 1) following the completion of the current instruction.

### Set Overflow Flag (S.O.)

A NEGATIVE going edge on this input sets the overflow bit in the Status Code Register. This signal is sampled on the trailing edge of  $\phi_1$ .

### SYNC

This output line is provided to identify those cycles in which the microprocessor is doing an OP CODE fetch. The SYNC line goes high during  $\phi_1$  of an OP CODE fetch and stays high for the remainder of that cycle. If the RDY line is pulled low during the  $\phi_1$  clock pulse in which SYNC went high, the processor will stop in its current state and will remain in the state until the RDY line goes high. In this manner, the SYNC signal can be used to control RDY to cause single instruction execution.

### Reset ( $\overline{RES}$ )

This input is used to reset or start the microprocessor from a power down condition. During the time that this line is held low, writing to or from the microprocessor is inhibited. When a positive edge is detected on the input, the microprocessor will immediately begin the reset sequence.

After a system initialization time of six clock cycles, the mask interrupt flag will be set and the microprocessor will load the program counter from the memory vector locations FFFC and FFFD. This is the start location for program control.

After  $V_{CC}$  reaches 4.75 volts in a power up routine, reset must be held low for at least two clock cycles. At this time the  $R/\overline{W}$  and SYNC signal will become valid.

When the reset signal goes high following these two clock cycles, the microprocessor will proceed with the normal reset procedure detailed above.

### Read/Write ( $R/\overline{W}$ )

This output signal is used to control the direction of data transfers between the processor and other circuits on the data bus. A high level on  $R/\overline{W}$  signifies data into the processor; a low is for data transfer out of the processor.

## Programming Characteristics

### INSTRUCTION SET — ALPHABETIC SEQUENCE

ADC Add Memory to Accumulator with Carry	LDA Load Accumulator with Memory
AND "AND" Memory with Accumulator	LDX Load Index X with Memory
ASL Shift left One Bit (Memory or Accumulator)	LDY Load Index Y with Memory
BCC Branch on Carry Clear	LSR Shift One Bit Right (Memory or Accumulator)
BCS Branch on Carry Set	NOP No Operation
BEQ Branch on Result Zero	ORA "OR" Memory with Accumulator
BIT Test Bits in Memory with Accumulator	PHA Push Accumulator on Stack
BMI Branch on Result Minus	PHP Push Processor Status on Stack
BNE Branch on Result not Zero	PLA Pull Accumulator from Stack
BPL Branch on Result Plus	PLP Pull Processor Status from Stack
BRK Force Break	ROL Rotate One Bit Left (Memory or Accumulator)
BVC Branch on Overflow Clear	ROR Rotate One Bit Right (Memory or Accumulator)
BVS Branch on Overflow Set	RTI Return from Interrupt
CLC Clear Carry Flag	RTS Return from Subroutine
CLD Clear Decimal Mode	SBC Subtract Memory from Accumulator with Borrow
CLI Clear Interrupt Disable Bit	SEC Set Carry Flag
CLV Clear Overflow Flag	SED Set Decimal Mode
CMP Compare Memory and Accumulator	SEI Set Interrupt Disable Status
CPX Compare Memory and Index X	STA Store Accumulator in Memory
CPY Compare Memory and Index Y	STX Store Index X in Memory
DEC Decrement Memory by One	STY Store Index Y in Memory
DEX Decrement Index X by One	TAX Transfer Accumulator to Index X
DEY Decrement Index Y by One	TAY Transfer Accumulator to Index Y
EOR "Exclusive-or" Memory with Accumulator	TSX Transfer Stack Pointer to Index X
INC Increment Memory by One	TXA Transfer Index X to Accumulator
INX Increment Index X by One	TXS Transfer Index X to Stack Pointer
INY Increment Index Y by One	TYA Transfer Index Y to Accumulator
JMP Jump to New Location	
JSR Jump to New Location Saving Return Address	

### ADDRESSING MODES

#### Accumulator Addressing

This form of addressing is represented with a one byte instruction, implying an operation on the accumulator.

#### Immediate Addressing

In immediate addressing, the operand is contained in the second byte of the instruction, with no further memory addressing required.

#### Absolute Addressing

In absolute addressing, the second byte of the instruction specifies the eight low order bits of the effective address while the third byte specifies the eight high order bits. Thus, the absolute addressing mode allows access to the entire 65K bytes of addressable memory.

#### Zero page Addressing

The zero page instructions allow for shorter code and execution times by only fetching the second byte of the instruction and assuming a zero high address byte. Careful use of the zero page can result in significant increase in code efficiency.

#### Indexed Zero Page Addressing — (X, Y indexing)

This form of addressing is used in conjunction with the index register and is referred to as "Zero Page, X" or "Zero

Page, Y." The effective address is calculated by adding the second byte to the contents of the index register. Since this is a form of "Zero Page" addressing, the content of the second byte references a location in page zero. Additionally due to the "Zero Page" addressing nature of this mode, no carry is added to the high order 8 bits of memory and crossing of page boundaries does not occur.

#### Indexed Absolute Addressing — (X, Y indexing)

This form of addressing is used in conjunction with X and Y index register and is referred to as "Absolute, X," and "Absolute, Y." The effective address is formed by adding the contents of X or Y to the address contained in the second and third bytes of the instruction. This mode allows the index register to contain the index or count value and the instruction to contain the base address. This type of indexing allows any location referencing and the index to modify multiple fields resulting in reduced coding and execution time.

#### Implied Addressing

In the implied addressing mode, the address containing the operand is implicitly stated in the operation code of the instruction.

**Relative Addressing**

Relative addressing is used only with branch instructions and establishes a destination for the conditional branch.

The second byte of the instruction becomes the operand which is an "Offset" added to the contents of the lower eight bits of the program counter when the counter is set at the next instruction. The range of the offset is -128 to +127 bytes from the next instruction.

**Indexed Indirect Addressing**

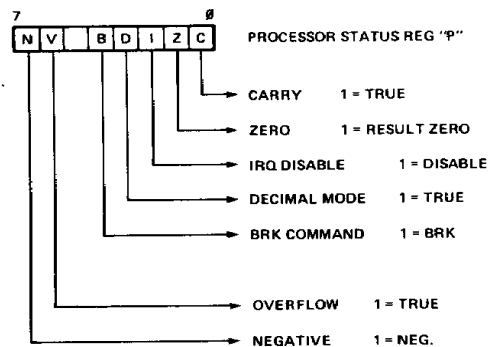
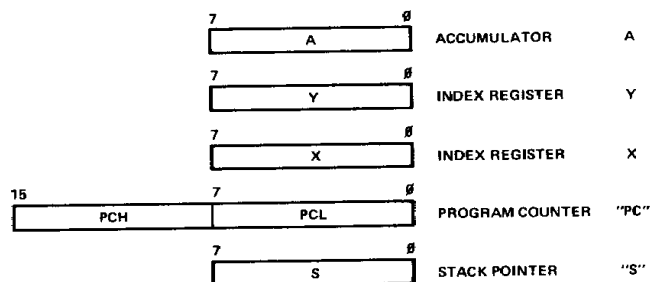
In indexed indirect addressing (referred to as (Indirect,X)), the second byte of the instruction is added to the contents of the X index register, discarding the carry. The result of this addition points to a memory location on page zero whose contents is the low order eight bits of the effective address. The next memory location in page zero contains the high order eight bits of the effective address. Both memory locations specifying the high and low order bytes of the effective address must be in page zero.

**Indirect Indexed Addressing**

In indirect indexed addressing (referred to as (Indirect,Y), the second byte of the instruction points to a memory location in page zero. The contents of this memory location is added to the contents of the Y index register, the result being the low order eight bits of the effective address. The carry from this addition is added to the contents of the next page zero memory location, the result being the high order eight bits of the effective address.

**Absolute Indirect**

The second byte of the instruction contains the low order eight bits of a memory location. The high order eight bits of that memory location is contained in the third byte of the instruction. The contents of the fully specified memory location is the low order byte of the effective address. The next memory location contains the high order byte of the effective address which is loaded into the sixteen bits of the program counter.

**Programming Characteristics****PROGRAMMING MODEL**



## INSTRUCTION SET — OP CODES, EXECUTION TIME, MEMORY REQUIREMENTS

INSTRUCTIONS		IMMEDIATE		ABSOLUTE		ZERO PAGE		ACCUM		IMPLIED		(IND X)		(IND Y)		Z PAGE X		ABS. X		ABS. Y		RELATIVE		INDIRECT		Z PAGE Y		CONDITION CODES						
MEMORIC	OPERATION	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	N	Z	C	I	D	V	
ADC	A ← M + C ← A (4) (1)	69	2	2	6D	4	3	65	3	2						61	6	2	71	5	2	75	4	2	7D	4	3	79	4	3				
AND	A ← M ← A (1)	29	2	2	2D	4	3	25	3	2						21	6	2	31	5	2	35	4	2	3D	4	3	39	4	3				
ASL	C ← <table border="1" style="display: inline-table; vertical-align: middle;"><tr><td>7</td></tr></table> ← 0	7				0E	6	3	06	5	2	0A	2	1																				
7																																		
BCC	BRANCH ON C=0	(2)																																
BCS	BRANCH ON C=1	(2)																																
BEQ	BRANCH ON Z=1	(2)																																
BIT	A ← M				2C	4	3	24	3	2																								
BMI	BRANCH ON N=1	(2)																																
BNE	BRANCH ON Z=0	(2)																																
BPL	BRANCH ON N=0	(2)																																
BRK	(See Fig. 1)																																	
BVC	BRANCH ON V=0	(2)																																
BVS	BRANCH ON V=1	(2)																																
CLC	0 ← C																																	
CLO	0 ← D																																	
CLI	0 ← I																																	
CLV	0 ← V																																	
CMP	A ← M (1)	C9	2	2	CD	4	3	C5	3	2																								
CPX	X ← M	E9	2	2	EC	4	3	E4	3	2																								
CPY	Y ← M	C9	2	2	CC	4	3	C4	3	2																								
DEC	M-1 ← M																																	
DEX	X-1 ← X																																	
DEY	Y-1 ← Y																																	
EOR	A ← M ← A (1)	49	2	2	4D	4	3	45	3	2																								
INC	M+1 ← M																																	
INX	X+1 ← X																																	
INY	Y+1 ← Y																																	
JMP	JUMP TO NEW LOC																																	
JSR	(See Fig. 2) JUMP SUB																																	
LDA	M ← A (1)	A9	2	2	AD	4	3	A5	3	2																								

MNEUMONIC	OPERATION	IMMEDIATE		ABSOLUTE		ZERO PAGE		ACCUM		IMPLIED		IND. X		IND. Y		Z PAGE X		ABS. X		ABS. Y		RELATIVE		INDIRECT		Z PAGE Y		CONDITION CODES					
		OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	OP	N	N	Z	C	I	D	V
LDX	M ← X	(1) A2	2	2	AE	4	3	A6	3	2																86	4	2	✓	✓	—	—	—
LDY	M ← Y	(1) A9	2	2	AC	4	3	A4	3	2																		✓	✓	—	—	—	
LSR	0 → [7] → 0 → C				4E	6	3	46	5	2	4A	2	1															0	✓	✓	—	—	
NOP	NO OPERATION																																
ORA	A ← M ← A	99	2	2	0D	4	3	05	3	2				01	6	2	11	5	2	15	4	2	1D	4	3	19	4	3			✓	✓	—
PHA	A → Ms S-1 → S										48	3	1																				
PHP	P → Ms S-1 → S										08	3	1																				
PLA	S+1 → S Ms → A										68	4	1																				
PLP	S+1 → S Ms → P										28	4	1																				
ROL	[7] ← 0 ← C				2E	6	3	26	5	2	2A	2	1																				
ROR	[C] ← [7] ← 0				6E	6	3	66	5	2	6A	2	1																				
RTI	(See Fig. 1) RTRN INT										40	6	1																				
RTS	(See Fig. 2) RTRN SUB										60	6	1																				
SBC	A ← M ← A	(1) E9	2	2	ED	4	3	E5	3	2				E1	6	2	F1	5	2	F5	4	2	FD	4	3	F9	4	3			✓	✓	(3)
SEC	1 ← C										38	2	1																				
SED	1 ← D										FB	2	1																				
SEI	1 ← I										78	2	1																				
STA	A → M				8D	4	3	85	3	2				81	6	2	91	6	2	95	4	2	9D	5	3	99	5	3					
STX	X → M				8E	4	3	86	3	2																							
STY	Y → M				8C	4	3	84	3	2																							
TAX	A → X										AA	2	1																				
TAY	A → Y										AB	2	1																				
TSX	S → X										BA	2	1																				
TXA	X → A										8A	2	1																				
TXS	X → S										9A	2	1																				
TYA	Y → A										98	2	1																				

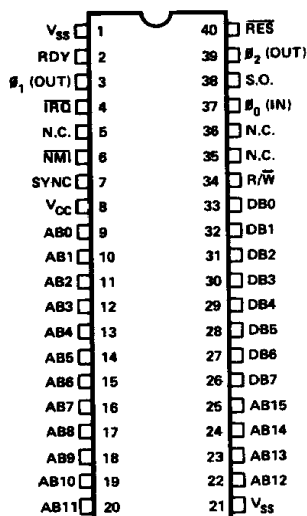
- (1) ADD 1 TO "N" IF PAGE BOUNDARY IS CROSSED  
 (2) ADD 1 TO "N" IF BRANCH OCCURS TO SAME PAGE  
 ADD 2 TO "N" IF BRANCH OCCURS TO DIFFERENT PAGE  
 (3) CARRY NOT = BELOW  
 (4) IF IN DECIMAL MODE Z FLAG IS INVALID  
 ACCUMULATOR MUST BE CHECKED FOR ZERO RESULT

X INDEX X  
 Y INDEX Y  
 A ACCUMULATOR  
 M MEMORY PER EFFECTIVE ADDRESS  
 Ms MEMORY PER STACK POINTER

+ ADD  
 - SUBTRACT  
 ^ AND  
 v OR  
 v EXCLUSIVE OR  
 v MODIFIED

- NOT MODIFIED  
 M<sub>7</sub> MEMORY BIT 7  
 M<sub>6</sub> MEMORY BIT 6  
 N NO CYCLES  
 # NO BYTES

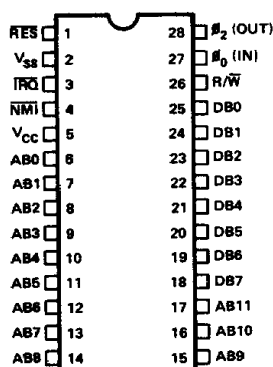
## SY6502 — 40 Pin Package



## Features

- 65K Addressable Bytes of Memory
- $\overline{\text{IRQ}}$  Interrupt
- $\overline{\text{NMI}}$  Interrupt
- On-the-chip Clock
  - ✓ TTL Level Single Phase Input
  - ✓ Crystal Time Base Input
- SYNC Signal  
(can be used for single instruction execution)
- RDY Signal  
(can be used for single cycle execution)
- Two Phase Output Clock for Timing of Support Chips

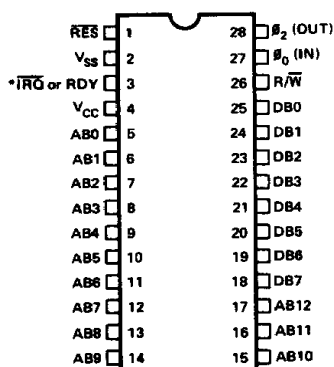
## SY6503 — 28 Pin Package



## Features

- 4K Addressable Bytes of Memory (AB00-AB11)
- On-the-chip Clock
- $\overline{\text{IRQ}}$  Interrupt
- $\overline{\text{NMI}}$  Interrupt
- 8 Bit Bi-Directional Data Bus

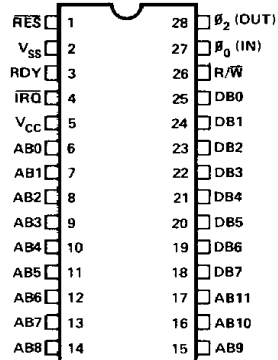
## SY6504 &amp; SY6507 — 28 Pin Package



## Features

- $\overline{\text{IRQ}}$  Interrupt (6504 only)
- RDY Signal (6507 only)
- 8K Addressable Bytes of Memory (AB00-AB12)
- On-the-chip Clock
- 8 Bit Bi-Directional Data Bus

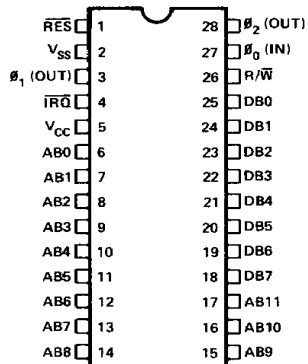
## SY6505 — 28 Pin Package



## Features

- 4K Addressable Bytes of Memory (AB00-AB11)
- On-the-chip Clock
- $\overline{\text{IRQ}}$  Interrupt
- RDY Signal
- 8 Bit Bi-Directional Data Bus

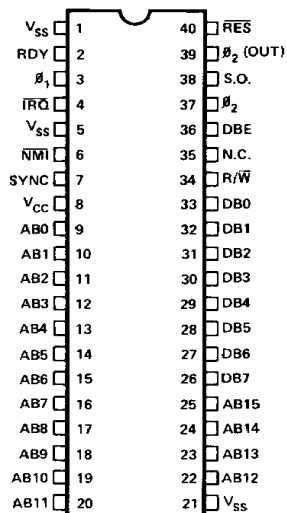
## SY6506 — 28 Pin Package



## Features

- 4K Addressable Bytes of Memory (AB00-AB11)
- On-the-chip Clock
- $\overline{\text{IRQ}}$  Interrupt
- Two phases off
- 8 Bit Bi-Directional Data Bus

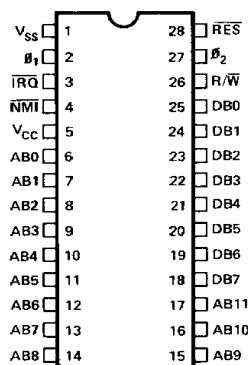
## SY6512 — 40 Pin Package



## Features

- 65K Addressable Bytes of Memory
- $\overline{\text{IRQ}}$  Interrupt
- NMI Interrupt
- RDY Signal
- 8 Bit Bi-Directional Data Bus
- SYNC Signal
- Two phase input
- Data Bus Enable

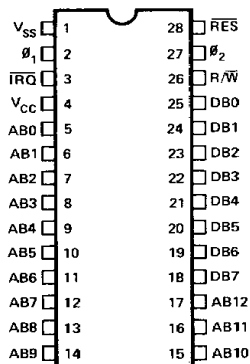
## SY6513 — 28 Pin Package



## Features

- 4K Addressable Bytes of Memory (AB00-AB11)
- Two phase clock input
- $\overline{\text{IRQ}}$  Interrupt
- $\overline{\text{NMI}}$  Interrupt
- 8 Bit Bi-Directional Data Bus

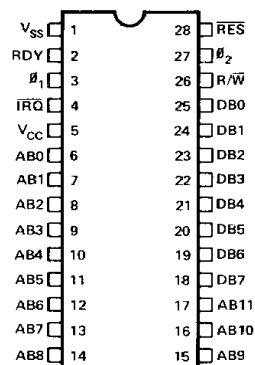
## SY6514 — 28 Pin Package



## Features

- 8K Addressable Bytes of Memory (AB00-AB12)
- Two phase clock input
- $\overline{\text{IRQ}}$  Interrupt
- 8 Bit Bi-Directional Data Bus

## SY6515 — 28 Pin Package

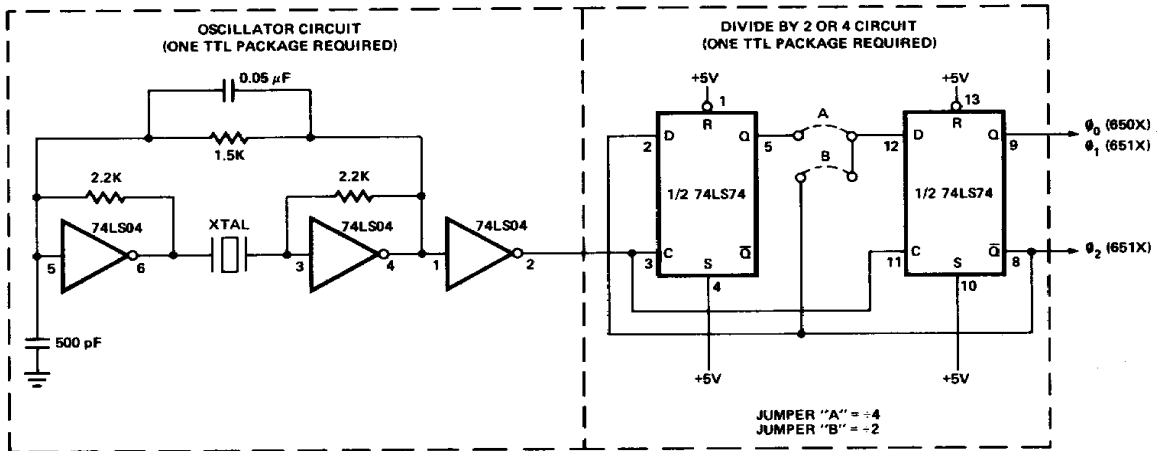


## Features

- 4K Addressable Bytes of Memory (AB00-AB11)
- Two phase clock input
- $\overline{\text{IRQ}}$  Interrupt
- 8 Bit Bi-Directional Data Bus

# Clock Generation Circuits\*

\*For further details refer to Synertek SY6500 Applications Information Note AN2. Crystals used are CTS Knight MP Series or equivalents. (Series Mode)



CRYSTAL FREQUENCY	OUTPUT FREQUENCY	
	$\div 2$	$\div 4$
3.579545 MHz	1.7897 MHz	0.894886 MHz
4.194304 MHz	2.097152 MHz	1.048576 MHz

